

Title (en)  
Double-sided package

Title (de)  
Doppelseitige Verpackung

Title (fr)  
Emballage double face

Publication  
**EP 2763163 A2 20140806 (EN)**

Application  
**EP 14152487 A 20140124**

Priority  
US 201313757299 A 20130201

Abstract (en)

Various embodiments of an integrated device package are disclosed herein. The package may include a leadframe having a first side and a second side opposite the first side. The leadframe can include a plurality of leads surrounding a die mounting region. A first package lid may be mounted on the first side of the leadframe to form a first cavity, and a first integrated device die may be mounted on the first side of the leadframe within the first cavity. A second integrated device die can be mounted on the second side of the leadframe. At least one lead of the plurality of leads can provide electrical communication between the first integrated device die and the second integrated device die.

IPC 8 full level

**H01L 23/04** (2006.01); **G01P 1/02** (2006.01); **H01L 23/10** (2006.01); **H01L 23/31** (2006.01); **H01L 23/495** (2006.01)

CPC (source: EP US)

**H01L 23/04** (2013.01 - EP US); **H01L 23/10** (2013.01 - EP US); **H01L 23/3107** (2013.01 - EP US); **H01L 23/49575** (2013.01 - EP US);  
**H01L 24/03** (2013.01 - EP US); **G01P 1/023** (2013.01 - EP US); **H01L 2924/1461** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US)

C-Set (source: EP US)

1. **H01L 2924/1461 + H01L 2924/00**
2. **H01L 2924/181 + H01L 2924/00**

Cited by

CN113823626A

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**EP 2763163 A2 20140806; EP 2763163 A3 20151118; US 2014217566 A1 20140807; US 9209121 B2 20151208**

DOCDB simple family (application)

**EP 14152487 A 20140124; US 201313757299 A 20130201**